Sheet 1 of 1 sheet(s) U.S. Department of Commerce, Patent and Trademark Office Docket No. Serial No. (PTO Form 1449 modified) AMAT/6551/CMI/TICL/ 10/033,544 **RKK** INFORMATION DISCLOSURE STATEMENT BY APPLICATION **Applicant** Confirmation No.: Hytros, et al. 7363 (Use several sheets if necessary) Filing Date Group SOM TRADE Examiner: December 27, 2001 Unknown **U.S. Patent Documents Document** Applicant(s) Class Filing Date If *Examiner Issue Subclass Number Initial Date Name Appropriate 6,200,844 03/13/2001 438 238 **A1** 02/12/1999 Huang Majewski et al. **A2** 6,148,761 11/21/2000 715 12/09/1998 118 **A3** 07/11/2000 6,086,677 Umotoy et al. 118 715 06/16/1998 10/19/1999 5,970,378 438 A4 Shue et al. 656 07/23/1997 **A5** 5,956,595 438 398 09/21/1999 Zenke 07/15/1997 **A6** 5,871,586 715 02/16/1999 Crawley et al. 04/09/1997 118 **A7** 5,665,640 09/09/1997 Foster et al. 680 438 06/03/1994 5,576,071 **8A** 11/19/1996 Sandhu 427 534 11/08/1994 A9 5,567,483 10/22/1996 Foster et al. 427 535 06/05/1995 Eichman et al. 5,308,655 05/03/1994 A10 427 248.1 02/10/1992 **A11** 5,279,857 01/18/1994 08/16/1991 Eichman et al. 427 255 F reign Patent Documents *Examiner Document Date Country Class Subclass Translation Initial Number YES NO 63-22984 **B1** 09/26/1988 JP H01L 12/28 **B2** 0711846 05/15/1996 EP **C23C** 16/34 **OTHER ART** *Examiner Including Author, Title, Date, Pertinent Pages, Etc. Initial W Arena, et al., "A New Low Temperature PECVD TiN Compatible With Multilevel Vias Application", C1 VMIC Conference, pp. 566-71, June 18-20, 1996 Allendorf, et al., "Chemical Vapor Deposition", Proceedings of the Fourteenth International C2 Conference and EUROCVD-11, Vol. 97-25, pp. 1625-33. Konecni, et al., "A Stable Plasma Treated CVD Titanium Nitride Film for Barrier/Glue Layer C3 Applications", VMIC Conference, pp. 181-3. Kim, et al., "Effect of N₂/H_x Plasma Treatment on the Properties of TiN Films Prepared by Chemical **C**4 Vapor Deposition from TiCl4 and NH₃", Jap. J. Appl. Phys., Vol. 38, Part 2, No. 4B, pp. L461-3, April 15, 1999

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